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02/07/01

Inventor(s):

Title: PLANARIZED SEMICONDUCTOR
INTERCONNECT TOPOGRAPHY
AND METHOD FOR POLISHING
A METAL LAYER TO FORM
INTERCONNECT

"Express Mail" mailing label no. EL726370210US
Date of Deposit: February 7, 2001


Derrick Brown

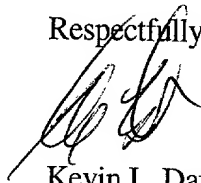
(For new non-provisional applications under 37 CFR § 1.53(b))

Enclosed are the following items:

1. A fee authorization for the amount of \$710.00.
2. Request & Certification under 35 U.S.C. 122(b)(2)(B)(i).
3. Specification as originally submitted including informal drawings.
4. Formal drawings of Figs. 1 - 8 on 3 sheets.
5. Copy of Declaration/Power of Attorney from prior application (see 37 CFR 1.63(d)).
6. Copy of Assignment papers from prior application.
7. Information Disclosure Statement w/form PTO-1449.
8. Return receipt postcard(s).

Please amend the specification by inserting before the first line the sentence: --This is a continuation application from prior application no. 09/143,723, filed August 31, 1998.

Respectfully submitted,



Kevin L. Daffer

Reg. No. 34,146

Attorney for Applicants

Conley, Rose & Tayon
P.O. Box 398
Austin, TX 78767-0398
Date: February 7, 2001

Atty. Dkt. No. 5298-02501
PM98019C

Inventor(s):

Anantha R. Sethuraman
Christopher A. Seams

Title: PLANARIZED SEMICONDUCTOR
INTERCONNECT TOPOGRAPHY
AND METHOD FOR POLISHING
A METAL LAYER TO FORM
INTERCONNECT

CERTIFICATE OF EXPRESS MAIL
UNDER 37 C.F.R. § 1.10

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Derrick Brown

FEE AUTHORIZATION

Assistant Commissioner for Patents
Washington, D.C. 20231

The Commissioner is hereby authorized to charge the following fee to Conley, Rose & Tayon, P.C. deposit account no. 50-1505/5298-02501*.

Item:	Filing fee
Amount:	\$710.00
Atty. Dkt. No.	5298-02501

Respectfully submitted,

Kevin L. Daffer
Reg. No. 34,146
Attorney for Applicants

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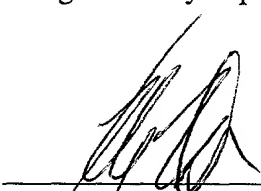
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<p align="center">CERTIFICATE OF EXPRESS MAIL UNDER 37 C.F.R. §1.10</p> <p>"Express Mail" mailing label number: EL726370210US DATE OF DEPOSIT: February 7, 2001</p> <p>I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 C.F.R. §1.10 on the date indicated above and is addressed to:</p> <p align="center">Assistant Commissioner for Patents Box Patent Application Washington, DC 20231</p> <p align="center"> Derrick Brown</p>	<p align="center">REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b)(2)(B)(i)</p> <table border="1"> <tr> <td>Atty Docket Number:</td> <td>5298-02501</td> </tr> <tr> <td>First Named Inventor:</td> <td>Anantha R. Sethuraman et al.</td> </tr> <tr> <td>Title:</td> <td>PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT</td> </tr> </table>	Atty Docket Number:	5298-02501	First Named Inventor:	Anantha R. Sethuraman et al.	Title:	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT
Atty Docket Number:	5298-02501						
First Named Inventor:	Anantha R. Sethuraman et al.						
Title:	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT						

I hereby certify that the invention disclosed in the attached application **has not and will not be** the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

February 7, 2001

Date


Kevin L. Daffer, Reg. No. 34,146

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**

Burden Hour Statement: This collection of information is required by 37 CFR 1.213(a). The information is used by the public to request that an application not be published under 35 U.S.C. 122(b) (and the PTO to process that request). Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This form is estimated to take 6 minutes to complete. This time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.